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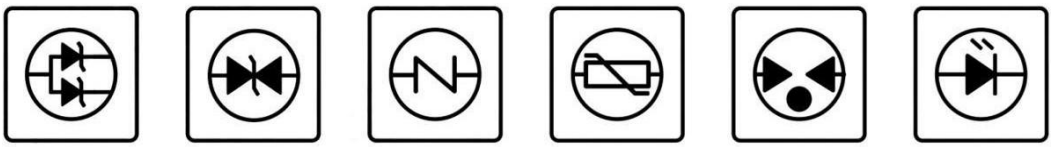
SEMICONDUCTOR



AON6362-MS

Product specification

Description

The AON6362-MS uses advanced trench technology to provide excellent RDS(ON) , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

Features

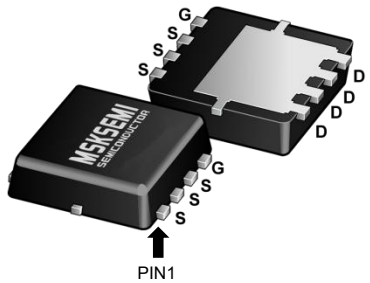
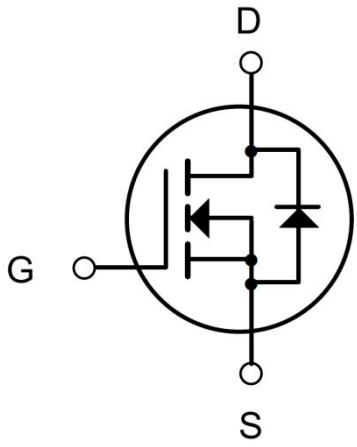
V_{DS} = 30V I_D =70A

$R_{DS(ON)}$ < 7mΩ V_{GS}=10V

Application

- Battery protection
- Load switch
- Uninterruptible power supply

Reference News

PACKAGE OUTLINE	N-Channel MOSFET	Marking
 DFN5X6-8L		

Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain- Source Voltage	30	V
V_{GS}	Gate- Source Voltage	±20	V
I_D @T_C=25℃	Continuous Drain Current, V_{GS} @ 10V [1]	70	A
I_D @T_C=100℃	Continuous Drain Current, V_{GS} @ 10V [1]	40	A
I_D @T_A=25℃	Continuous Drain Current, V_{GS} @ 10V [1]	30	A
I_D @T_A=70℃	Continuous Drain Current, V_{GS} @ 10V [1]	18	A
I_{DM}	Pulsed Drain Current[2]	140	A
EAS	Single Pulse Avalanche Energy[3]	115.2	mJ
I_{AS}	Avalanche Current	48	A
P_D@T_C=25℃	Total Power Dissipation[4]	59	W
P_D@T_A=25℃	Total Power Dissipation[4]	2	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃
$R_{\theta JA}$	Thermal Resistance Junction- Ambient [1]	62	℃/ W
$R_{\theta JC}$	Thermal Resistance Junction- Case[1]	2.1	℃/ W

Electrical Characteristics (TC=25°C Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	30	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BVDSS Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.028	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=30A	---	5.7	7	mΩ
		V_{GS}=4.5V , I_D=15A	---	11	13	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.2	---	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-6.16	---	Mv/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=24V , V_{GS}=0V , T_J =25℃	---	---	1	uA
		V_{DS}=24V , V_{GS}=0V , T_J =55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}= ±20V , V_{DS}=0V	---	---	± 100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=30A	---	43	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	1.7	---	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=15V , V_{GS}=4.5V , I_D=15A	---	20	---	nC
Q_{gs}	Gate-Source Charge		---	7.6	---	
Q_{gd}	Gate-Drain Charge		---	7.2	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=15V , V_{GS}=10V , R_G=3.3 I_D=15A	---	7.8	---	ns
T_r	Rise Time		---	15	---	
$T_{d(off)}$	Turn-Off Delay Time		---	37.3	---	
T_f	Fall Time		---	10.6	---	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	2295	---	pF
C_{oss}	Output Capacitance		---	267	---	
C_{rss}	Reverse Transfer Capacitance		---	210	---	
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	81	A
I_{SM}	Pulsed Source Current[2,5]		---	---	160	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J =25℃	---	---	1	V
t_{rr}	Reverse Recovery Time	I_F=30A , dI/dt=100A/μs , T_J =25℃	---	14	---	nS
Q_{rr}	Reverse Recovery Charge		---	5	---	nC

Note :

1.The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0. 1mH,I_{AS}=48A

4.The power dissipation is limited by 150℃ junction temperature

5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

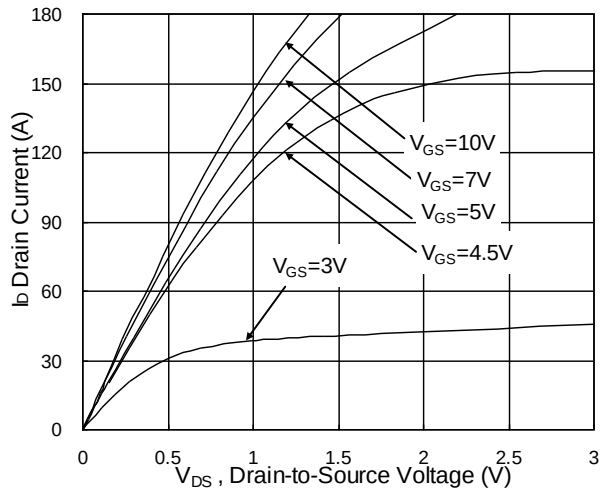


Fig.1 Typical Output Characteristics

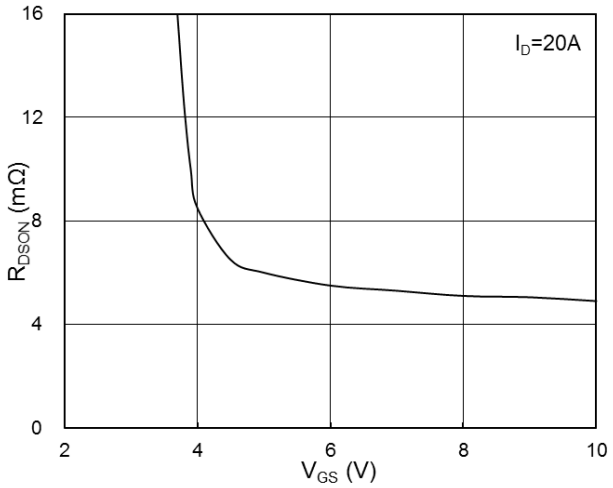


Fig.2 On-Resistance vs. G-S Voltage

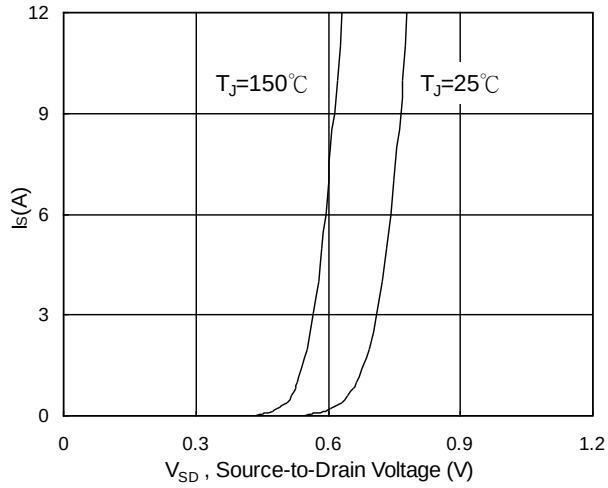


Fig.3 Forward Characteristics of Reverse

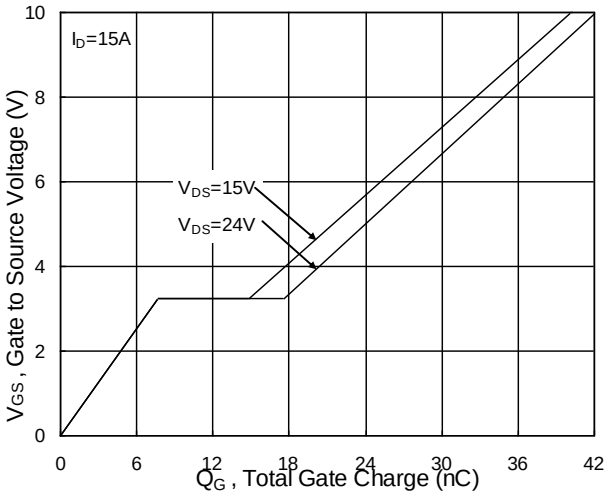


Fig.4 Gate-Charge Characteristics

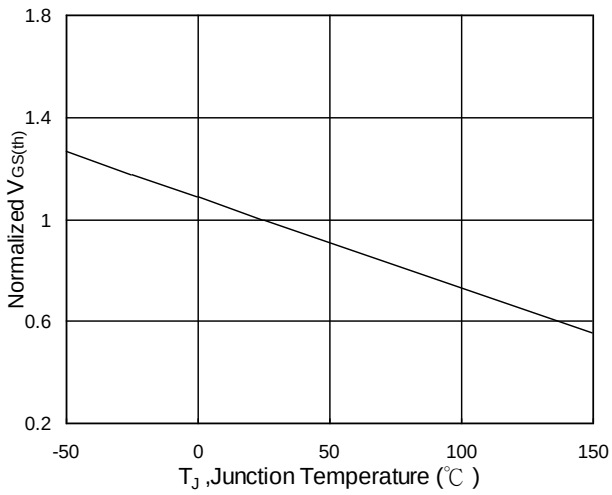


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

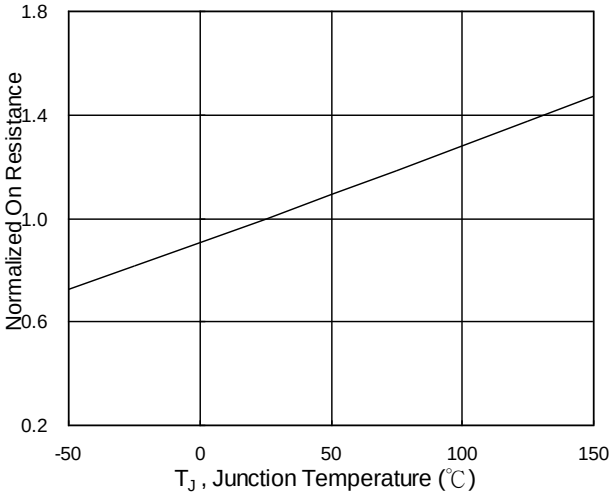


Fig.6 Normalized R_{DSON} vs. T_J

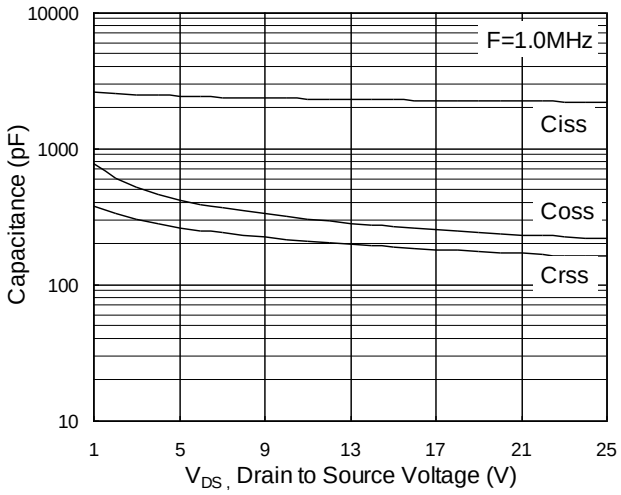


Fig.7 Capacitance

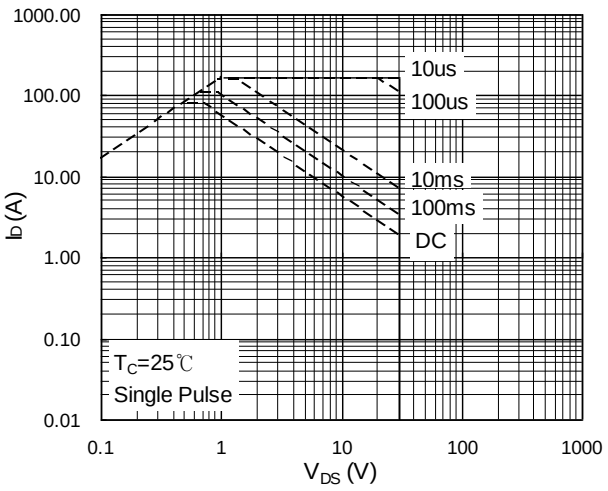


Fig.8 Safe Operating Area

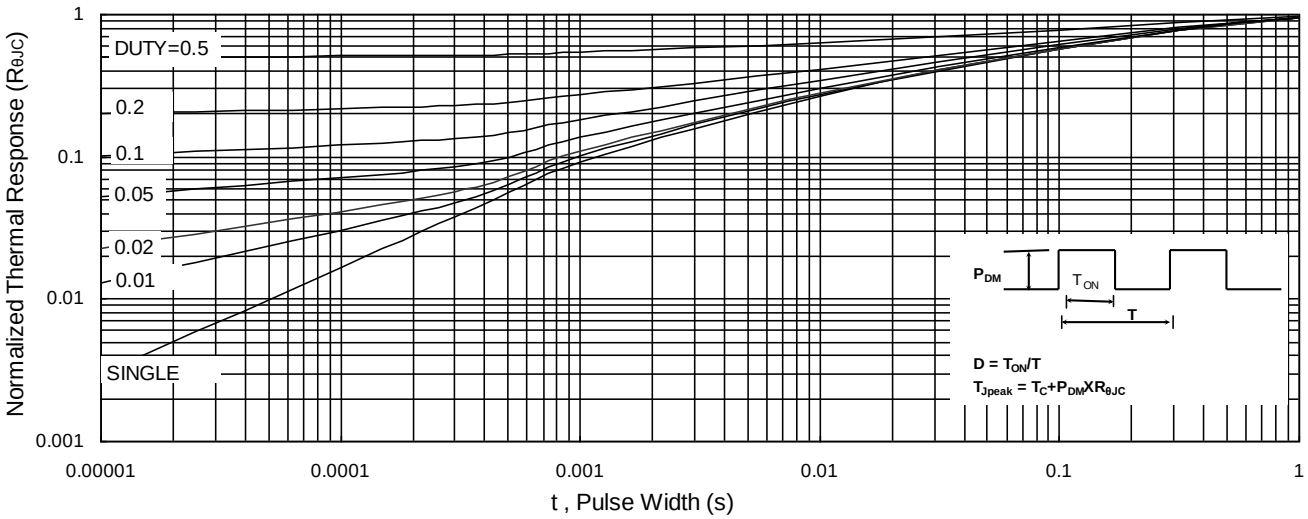


Fig.9 Normalized Maximum Transient Thermal Impedance

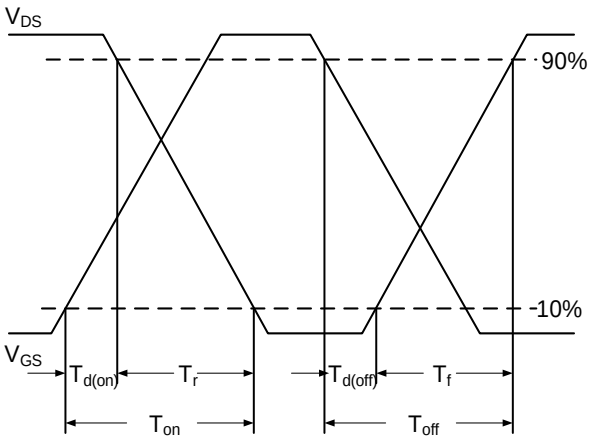


Fig.10 Switching Time Waveform

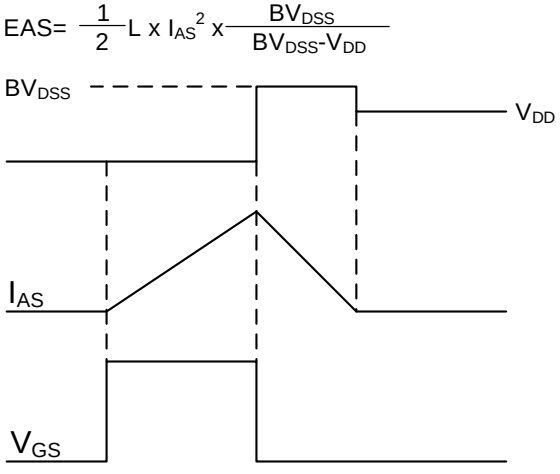
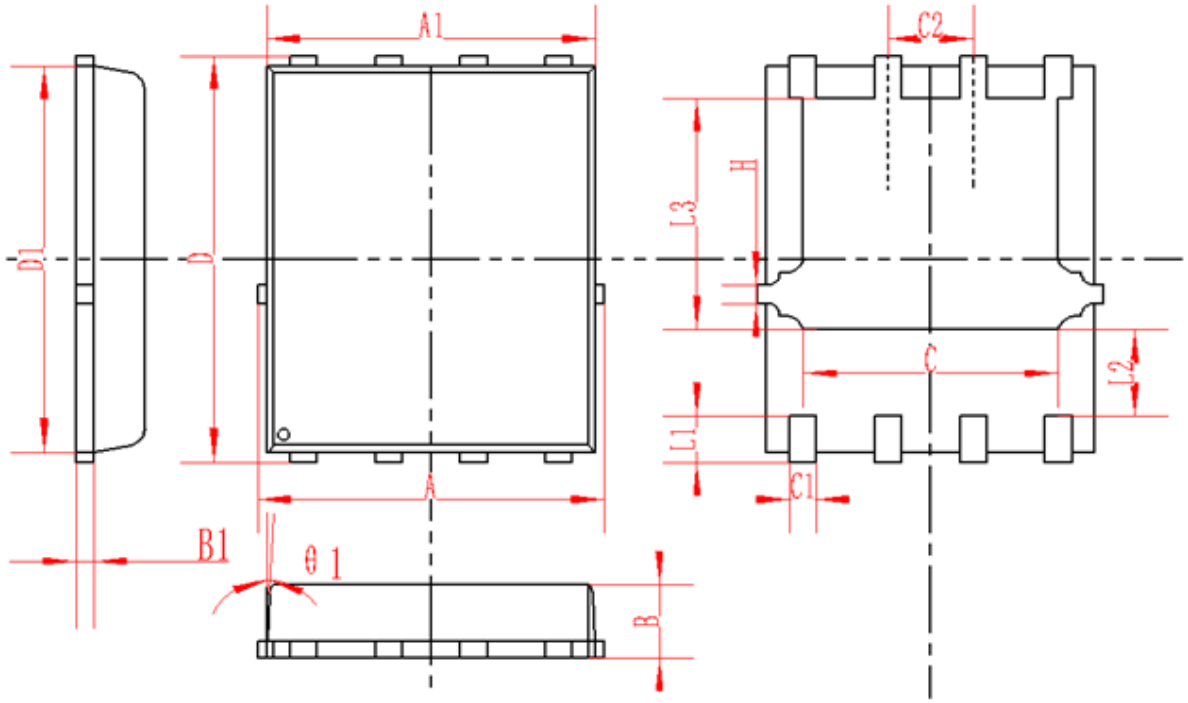


Fig.11 Unclamped Inductive Switching Waveform

DFN5X6-8L Package Information



SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
B	0.9	0.95	1	0.035	0.037	0.039
B1		0.254REF			0.010REF	
C	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2		1.27TYP			0.5TYP	
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
H	0.24	0.25	0.26	0.009	0.010	0.010

REEL SPECIFICATION

P/N	PKG	QTY
AON6362-MS	DFN5X6-8L	5000

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